

ABSTRACT

Provided is a wafer electroplating device, comprising: an electroplating tank, for containing an electroplating solution, an anode being arranged in the electroplating tank; a flow field plate, arranged between the anode and a wafer, the flow field plate being provided with a plurality of through-holes for the electroplating solution to pass through to form a flow field, the flow field plate including at least one flow field transition zone, and each flow field transition zone including at least two flow field zones with different resistivities; wherein, the maximum resistivity of each flow field transition zone is the minimum resistivity of the flow field on the side with the maximum resistivity of flow fields on both adjacent sides in the radial direction, or the minimum resistivity of the flow field transition zone is the maximum resistivity of the flow field on the side with the minimum resistivity of flow fields on both adjacent sides in the radial direction, and the flow field zone with the maximum resistivity or the flow field zone with the minimum resistivity in the flow field transition zone extends to the boundary of the flow field on the side having the same resistivity as the flow field zone. The wafer electroplating device of the present application enables uniform coating on the wafer.